

Title (en)

Electrical connecting device with high contact density.

Title (de)

Elektrische Verbindungsvorrichtung mit hoher Kontaktdichte.

Title (fr)

Dispositif de connexion électrique à haute densité de contacts.

Publication

EP 0053968 A1 19820616 (FR)

Application

EP 81401870 A 19811125

Priority

FR 8025861 A 19801205

Abstract (en)

[origin: US4445735A] The invention provides an electrical connection device for connecting high density contacts of large scale integrated circuits (LSI) and serves to establish electrical connection between the contact areas (15) of the circuit network (14) on a substrate (11) for supporting integrated circuit devices (12) and the contact pads (18) of a conductor network (17) on a printed circuit card (13). The electric connection device comprises a plurality of conductive elements disposed within a housing (26) extending in a given direction. The conductive elements are electrically insulated one from the other and have contacts which are exposed through slots in the housing to connect to the areas (15) and pads (18). The conductive elements (29) are stacked in the given direction and are formed each with a conductor sheet (30) provided with two contact surfaces (31a, 32a) elastically movable in a plane normal to the given direction independently of the surfaces of contact of neighboring sheets. The conductor sheet are supported on elastically deformable rolls extending the length of the support means which enable the contact surfaces to be displaced and compensate for deformities in the substrate and manufacturing tolerances.

Abstract (fr)

L'invention se rapporte à un dispositif de connexion électrique, du type comprenant une pluralité d'éléments conducteurs disposés relativement à un moyen de support (26) s'étendant dans une direction donnée et électriquement isolés les uns des autres. Selon l'invention, lesdits éléments (29) sont empilés dans ladite direction et sont formés chacun d'une lame conductrice (30) pourvue de deux surfaces de contact (31a, 32a) élastiquement mobile dans un plan normal à ladite direction sensiblement indépendamment des surfaces de contact des lames voisines. L'invention s'applique notamment à la connexion à haute densité de contacts, pour circuits intégrés LSI par exemple.

IPC 1-7

H01R 23/72

IPC 8 full level

H01L 21/60 (2006.01); **H01R 11/01** (2006.01); **H01R 12/32** (2006.01); **H01R 12/55** (2011.01); **H05K 1/18** (2006.01); **H05K 3/32** (2006.01)

CPC (source: EP US)

H01R 12/714 (2013.01 - EP US)

Citation (search report)

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EP 0053968 A1 19820616; **EP 0053968 B1 19850130**; DE 3168702 D1 19850314; FR 2495846 A1 19820611; FR 2495846 B1 19840106; JP H0250589 B2 19901102; JP S57121176 A 19820728; US 4445735 A 19840501

DOCDB simple family (application)

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